

LF-MightyPix: A second HV-MAPS prototype for the LHCb Mighty Tracker

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Introduction

■ Upcoming experiments: High Luminosity

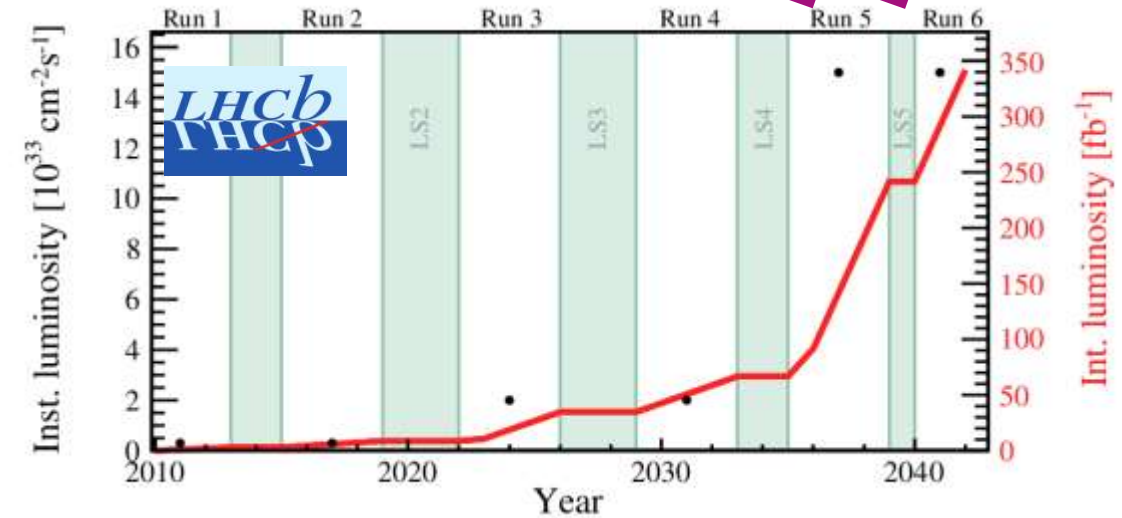
- High hit-rate capability
- High radiation hardness
- **Large area, $\sim O(10\text{m}^2)$**

→ Si pixel detectors are good candidates

- High granularity
- Radiation hardness has been studied extensively

→ Monolithic Active Pixel Sensor (MAPS)

- Simpler production process suitable for the large-scale production 😊
- Discontinuation of CMOS process might impact the project ☹️

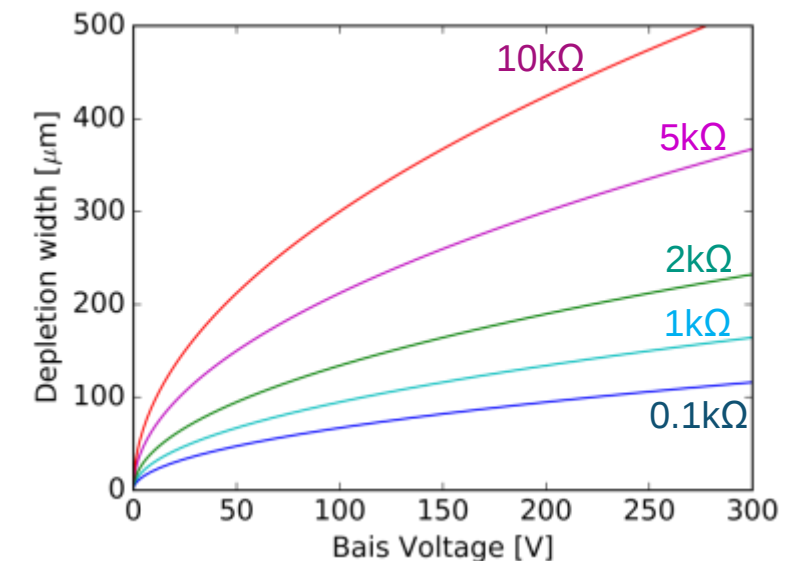
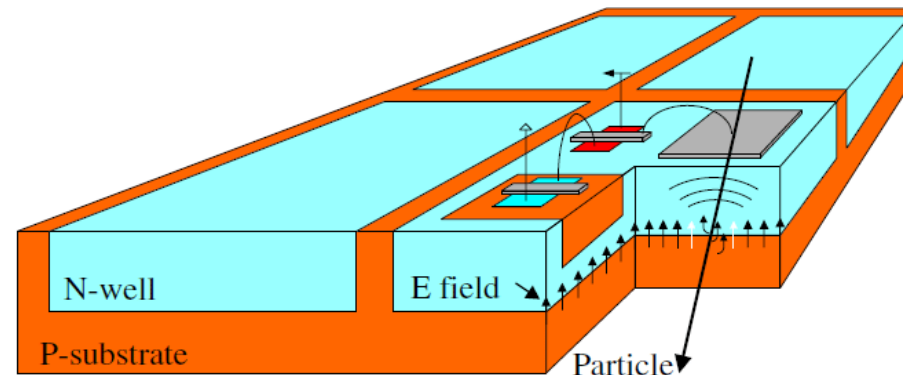


HV-MAPS

- High Voltage Monolithic Active Pixel Sensors (HV-MAPS) = MAPS + High Bias Voltage
 - MAPS: Sensor and readout in a single silicon chip
 - Readout electronics placed inside the n-well and isolated from sensor diode
 - High voltage (~100V) is possible to apply to the sensor diode and deplete sensor

$$\text{Depletion width } d \propto \sqrt{V_{bias} \cdot \rho_{material}}$$

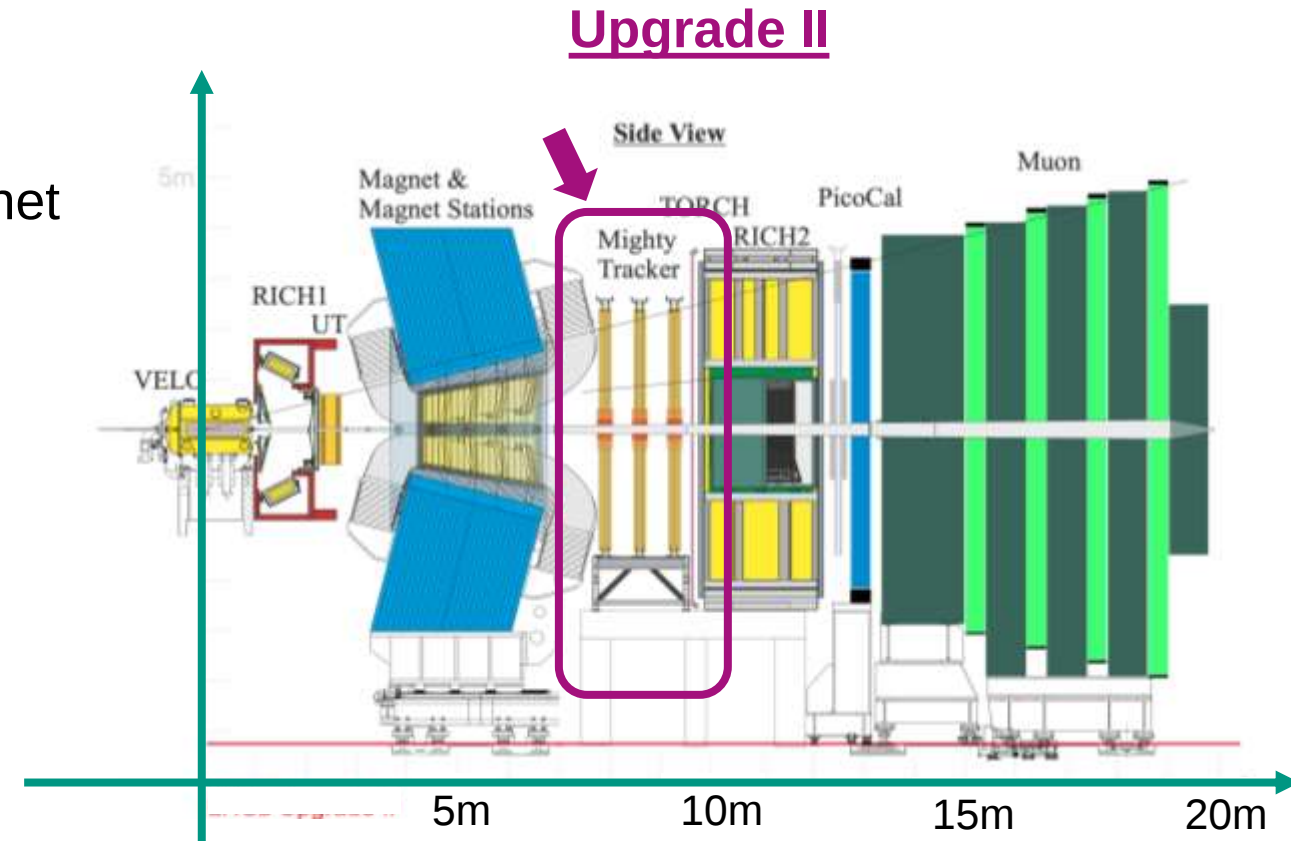
- Charge collection by drift (not diffusion)
- Higher radiation hardness



Mighty Tracker in LHCb experiments



- LHCb is a forward-arm spectrometer
- Upgrade I (SciFi Tracker)
 - 3 tracking stations downstream of the magnet
 - Scintillating fibers
 - Now in operation
- Upgrade II (Mighty Tracker)
 - 3 tracking stations
 - Scintillating fibers
 - **HV-MAPS**
 - Higher hit-rate capability and radiation hardness required to survive in Run 5, 6



MightyPix (HV-MAPS for Mighty Tracker)



Parameter	MP Specification
Pixel size (bending plane)	$\leq 100 \mu\text{m}$
Pixel size (non bending plane)	$\leq 200 \mu\text{m}$
Substrate thickness	$< 200 \mu\text{m}$
Pixel orientation	x
Max. Particle Rate	17 MHz/cm ²
Max. Hit Rate	34 Mhit s ⁻¹ cm ⁻²
Min. length of data word	32
Overall efficiency	>96%
Noise rate (End of life)	$\leq 400 \text{kHz/cm}^2$
Transmission rate	4 links of 1.28 Gbit/s each
NIEL	$3 \times 10^{14} n_{\text{eq}}/\text{cm}^2$
TID	40 MRad
Power Consumption	$\leq 150 \text{ mW/cm}^2$

Specifications for the LHCb MightyPix sensor, S. Bachmann et al., LHCb-INT In preparation

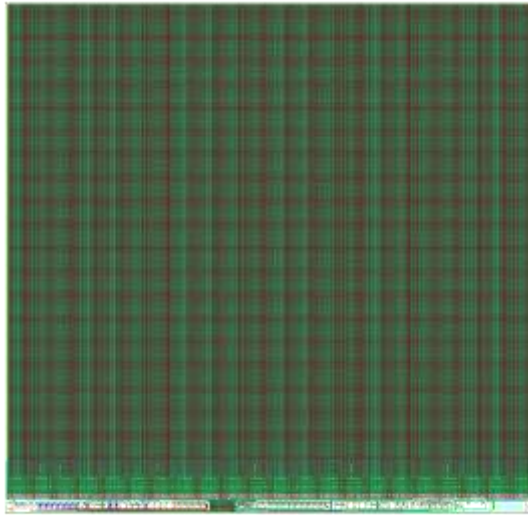
- Data Output
 - 4 output links or multiplexing to 2 or 1 output
 - 2 data formats: 48bit/hit 32bit/hit
 - DC-Balancing by multiplicative scrambler
- Experiment Control System
 - Multidrop downlink, daisy chain uplink to occupy min. number of eLinks
 - Chip configuration and tuning
 - Monitoring features (ADC, Status registers)
 - I2C interface for debugging
- Timing and Fast Control
 - 5 needed commands
- PLL, BX-CLK phase shifter
- Serial Powering Regulators

MightyPix Development

MightyPix1

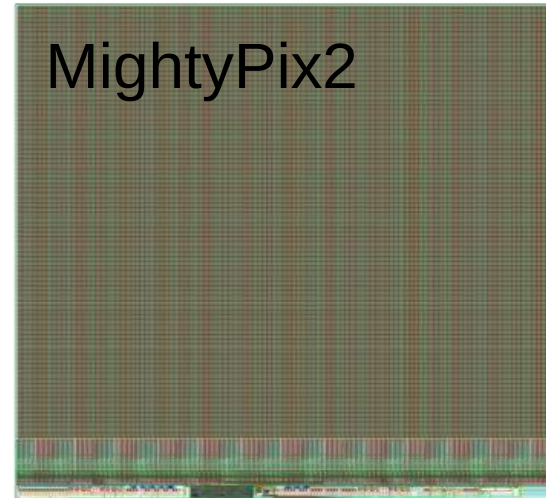


5 mm x 20 mm
180nm CMOS process
Basic LHCb specific
digital functions
(2022-2023)



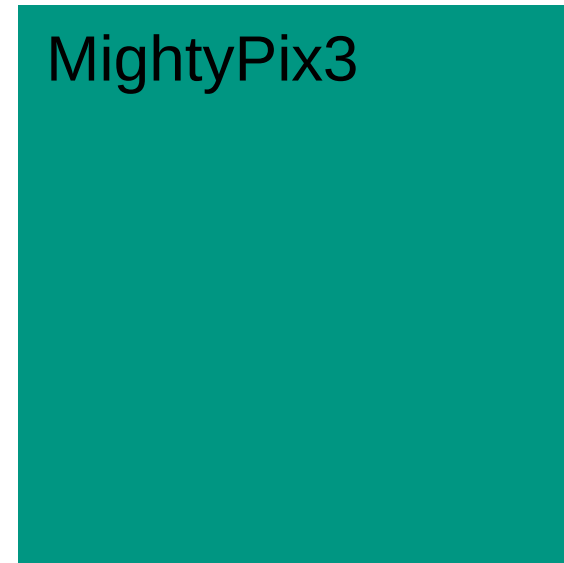
P2Pix

20 mm x 20 mm
180nm CMOS process
Mightypix identical analog matrix
(2024-2025)



MightyPix2

20 mm x 16 mm
180nm CMOS process
(Almost) Full LHCb specific
functions (2025-2026)

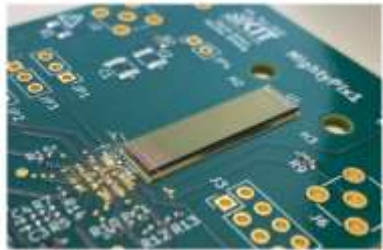


MightyPix3

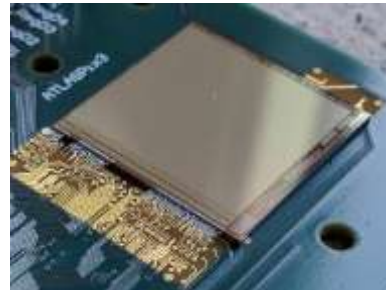
20 mm x 20 mm
180nm CMOS process
Final chip

HV-MAPS in alternative CMOS Process

- Further advantages of HV-MAPS: Several foundries can fabricate chips
 - Commercially available CMOS process
 - No change in CMOS process except resistivity of wafers for larger signal charge.
- ➡ Many types of HV-MAPS has been developed using different foundry, feature size, possible options to full fill each projects' requirements



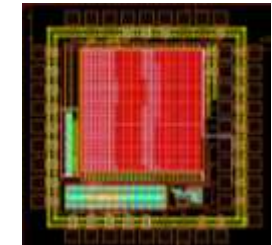
180nm CMOS process



180nm CMOS process



SiGe 130nm BiCMOS process



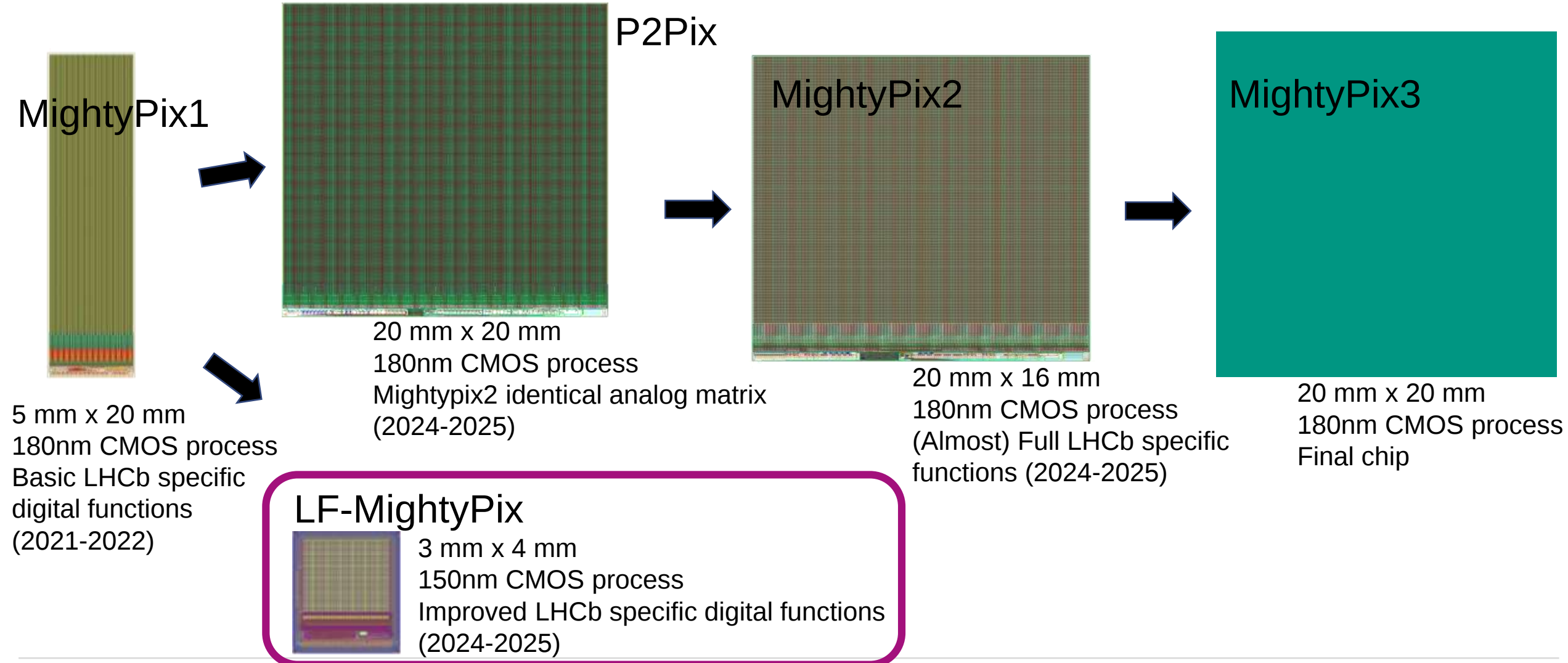
55nm CMOS process

- A prototype using another CMOS process as a backup
- LHCb specific digital function in silicon



HV-MAPS using 150nm CMOS

MightyPix Development



LF-MightyPix

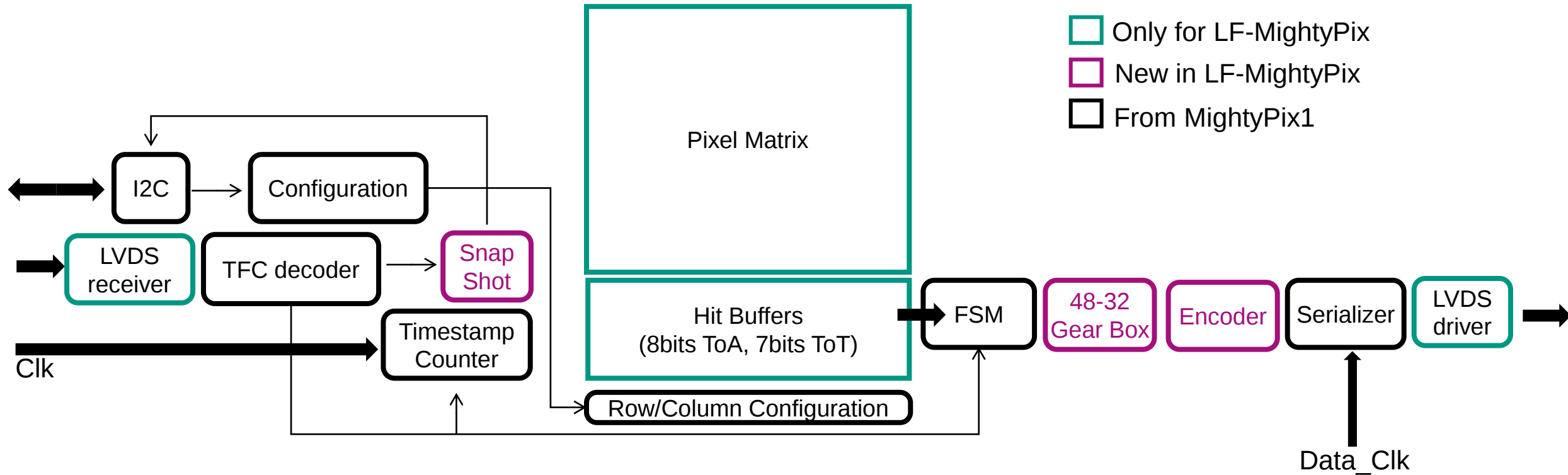


Parameter	MP Specification
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Pixel size (non bending plane)	$\leq 200 \mu\text{m}$ ✓
Substrate thickness	280 μm
Pixel orientation	x
Max. Particle Rate	17 MHz/cm ²
Max. Hit Rate	30M hits/s/cm²
Min. length of data word	48
Overall efficiency	>96%
Noise rate (End of life)	$\leq 400\text{kHz/cm}^2$
Transmission rate	1 links of 1.28Gbit/s each
NIEL	$3 \times 10^{14} n_{\text{eq}}/\text{cm}^2$
TID	40 MRad
Power Consumption	$\leq 150 \text{ mW/cm}^2$

Specifications for the LHCb MightyPix sensor, S. Bachmann et al.,
LHCb-INT In preparation

- Data Output
 - 4 Output links or multiplexing to 2 or 1 output
 - 2 data formats: **48bit/hit** 32bit/hit
 - DC-Balancing by multiplicative scrambler
- Experiment Control System
 - Multidrop downlink, daisy chain uplink to occupy min. number of eLinks
 - Chip configuration and tuning
 - Monitoring features (ADC, Status registers)
 - **I2C interface for debugging**
- Timing and Fast Control
 - **5 (4 + 0.5) needed commands**
- Clock and Reset
- Serial Powering Regulators

Block Diagram of LF-MightyPix



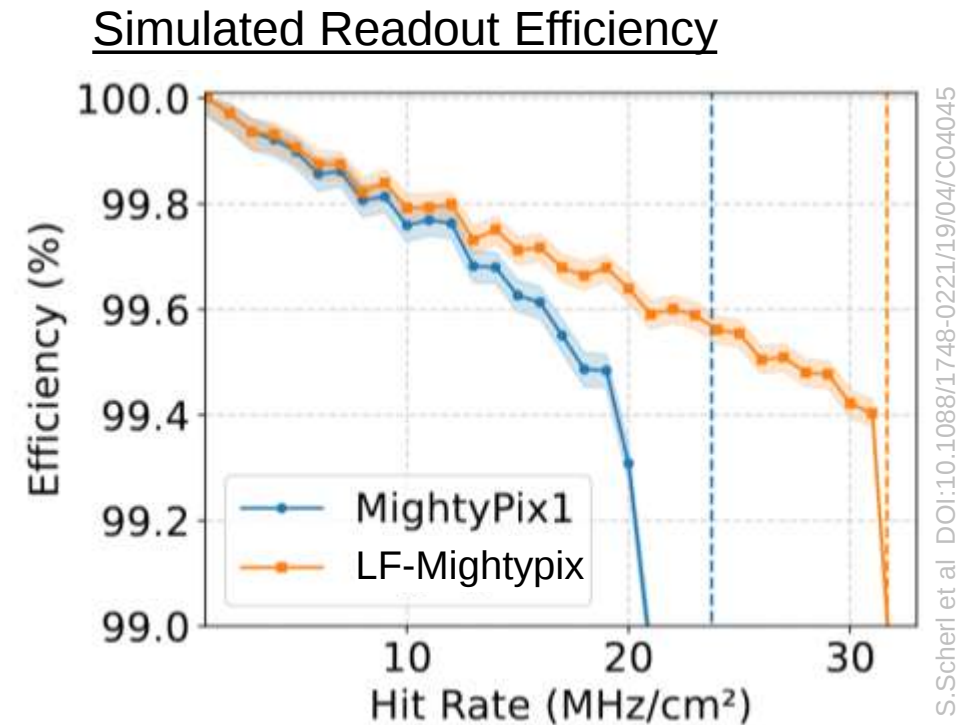
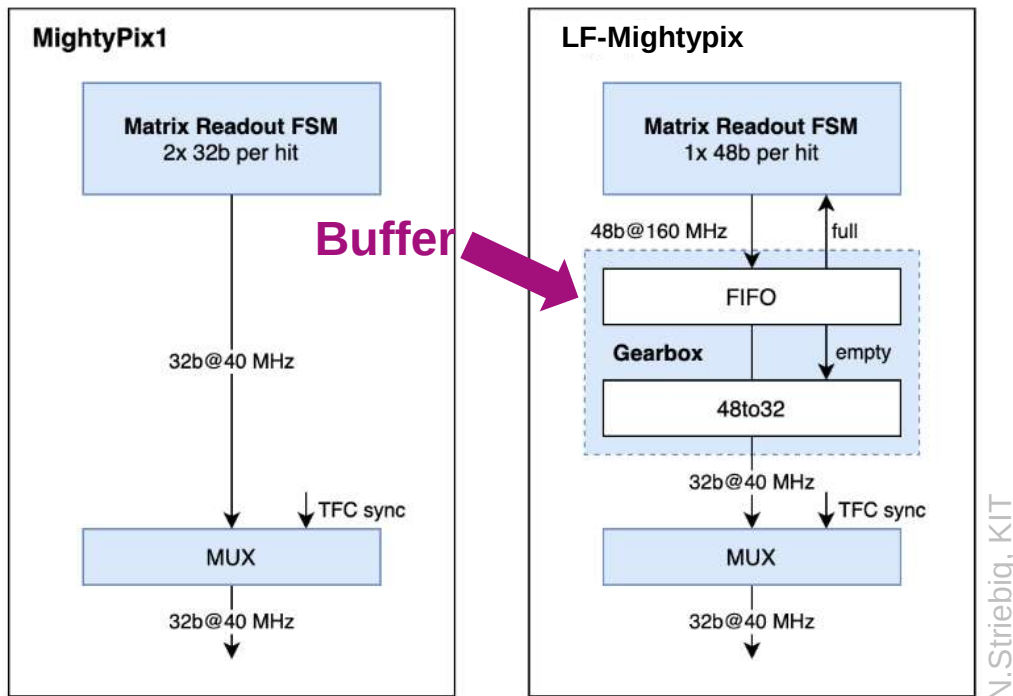
In-pixel readout, Hit buffer: customized for 150nm CMOS process

TFC, Data Links: implemented in 150nm CMOS process before implementing in large chip

New Features in LF-MightyPix

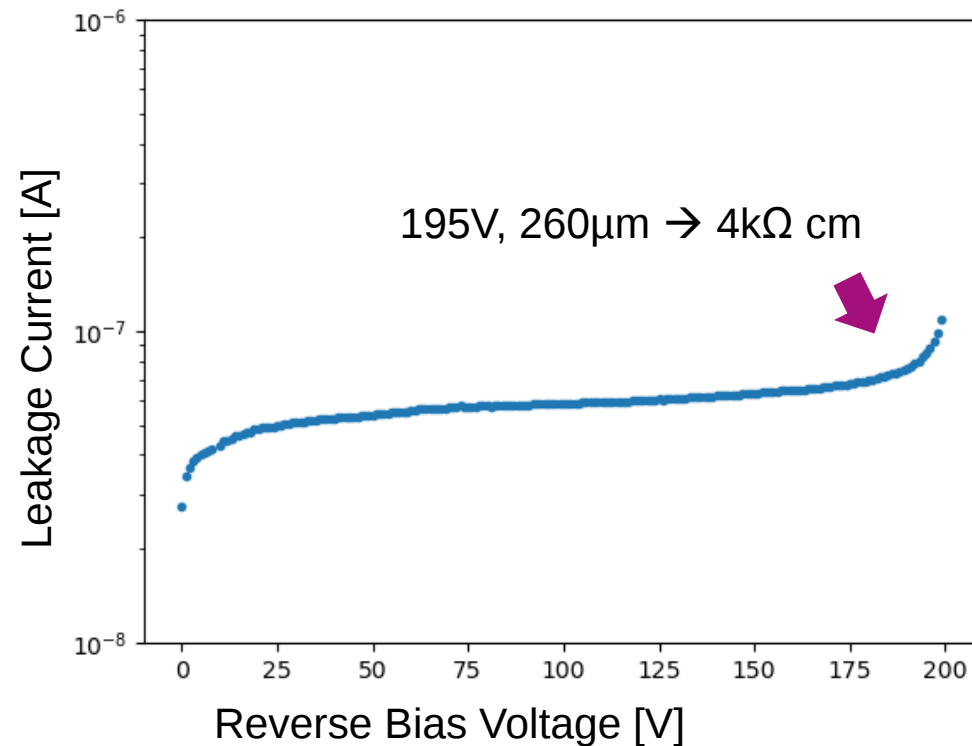


- 1.28Gbp data link: 32bits/packet
 - MightyPix1: 64bits/hit, $\sim 17\text{MHz/cm}^2$
 - LF-MightyPix : 48bits/hit, $\sim 30\text{ MHz/cm}^2$

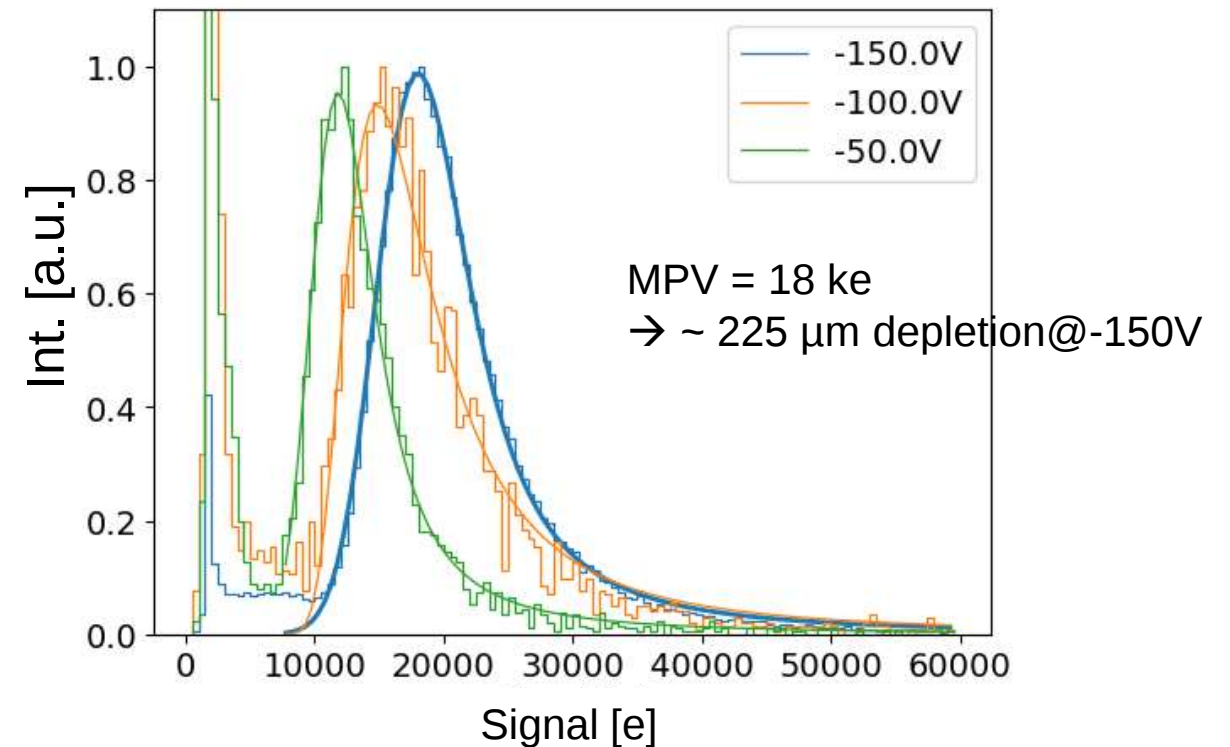


Sensor of LF-MightyPix

IV-Curve



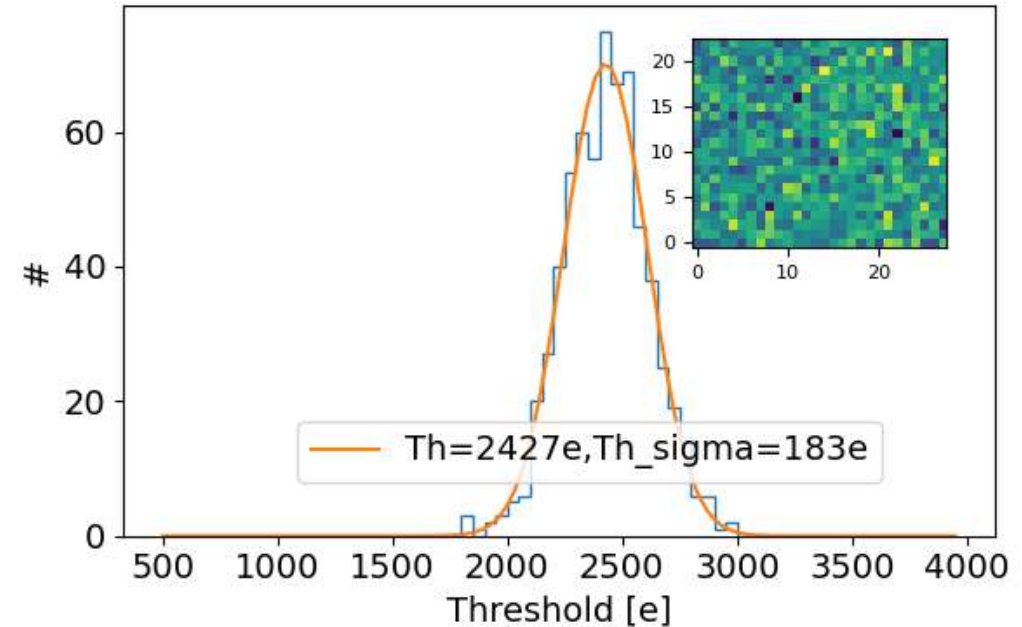
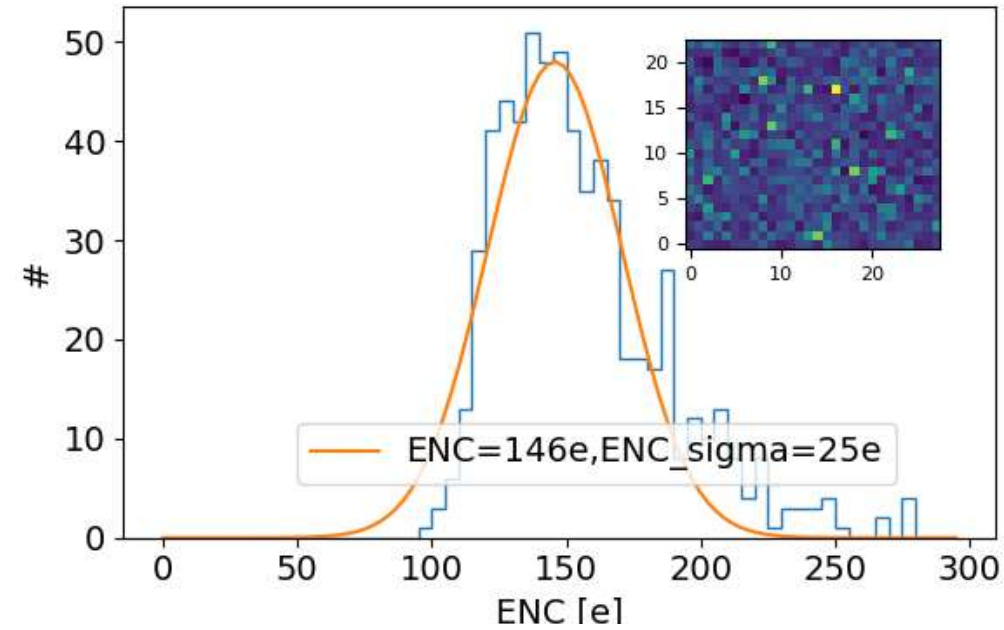
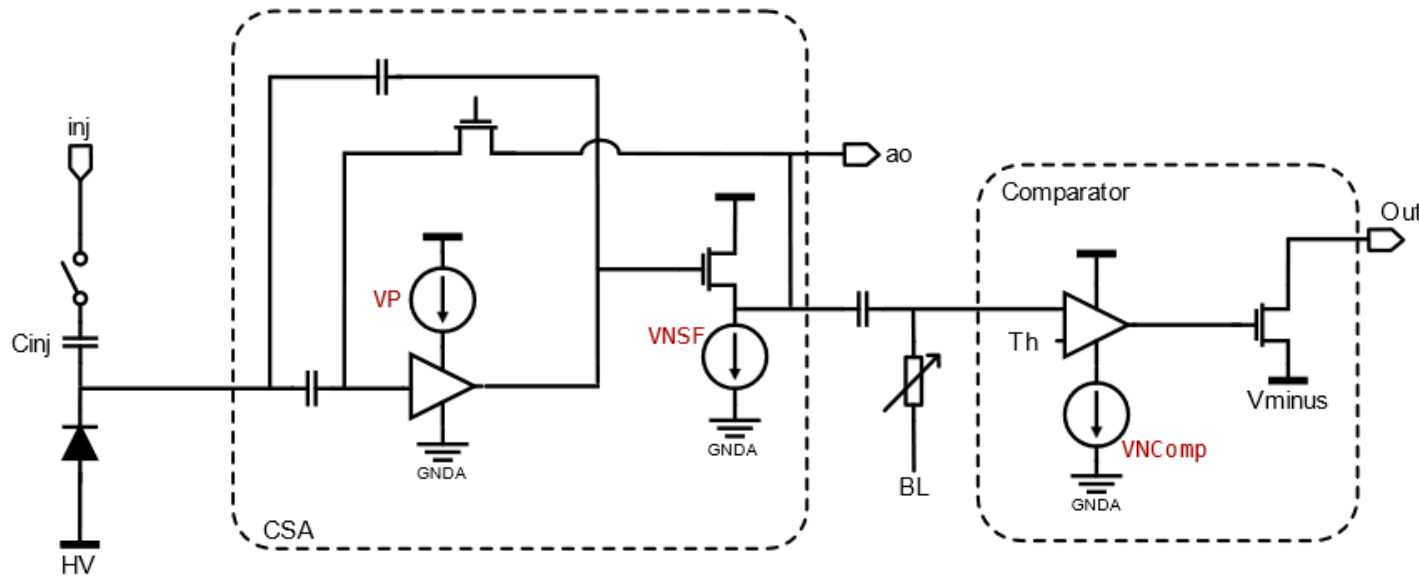
^{90}Sr Spectrum



Charge collection from sensor of > 200 μ m thickness

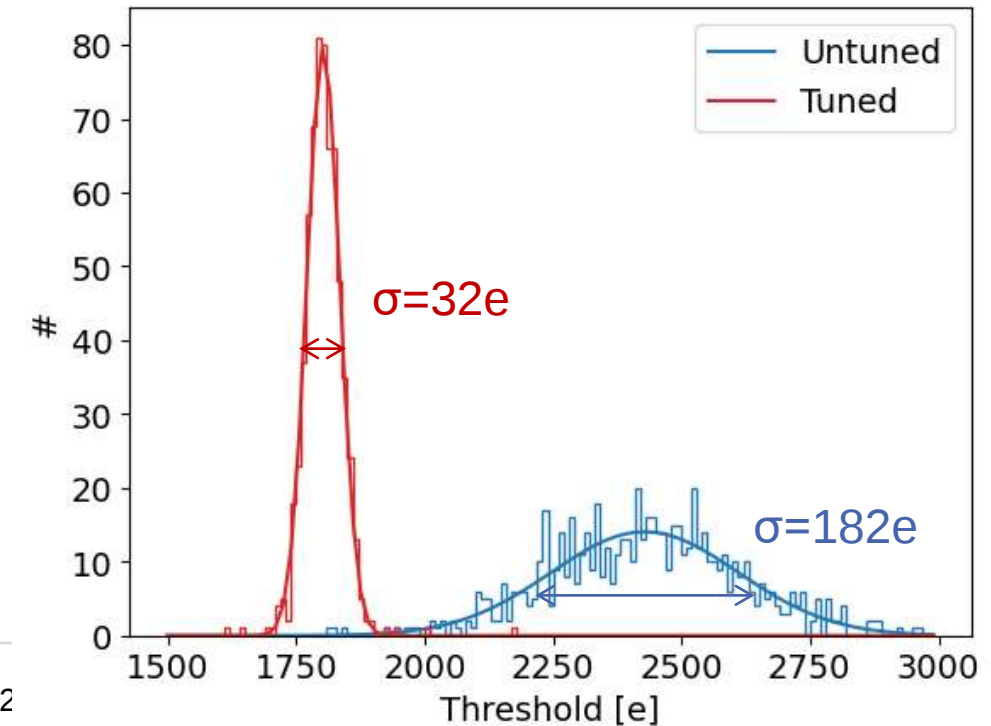
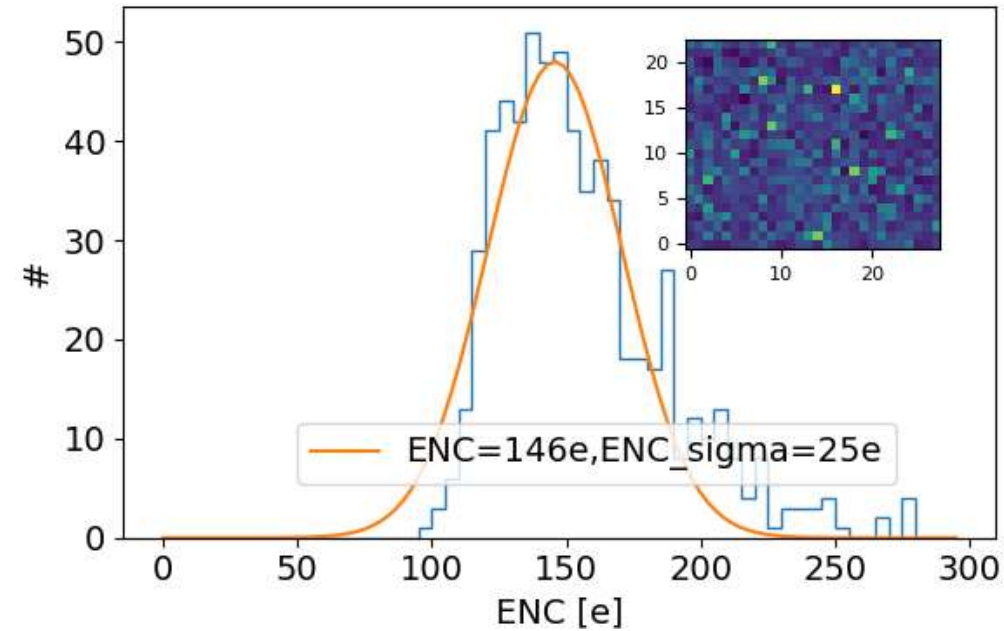
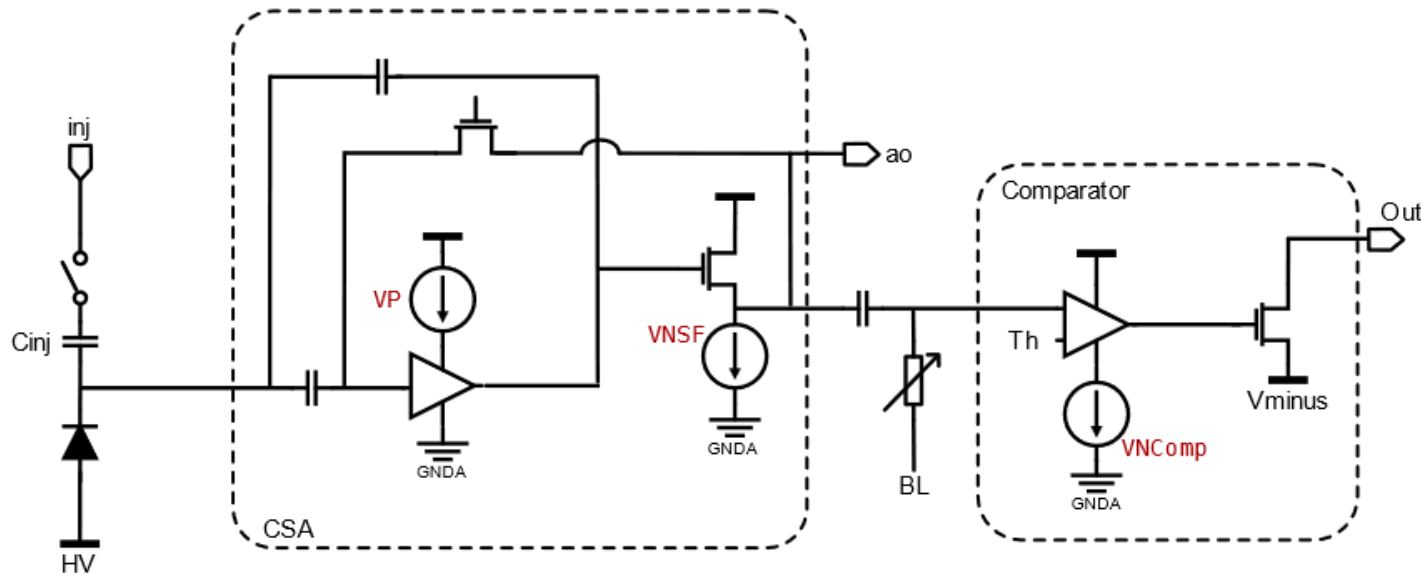
In-Pixel Readout of LF-MightyPix

- Designed and optimized for the 150nm CMOS process
- CSA + Comparator w/ 4bits fine Tuning DAC
 - ENC 146e
 - Thresholds are in a tunable range



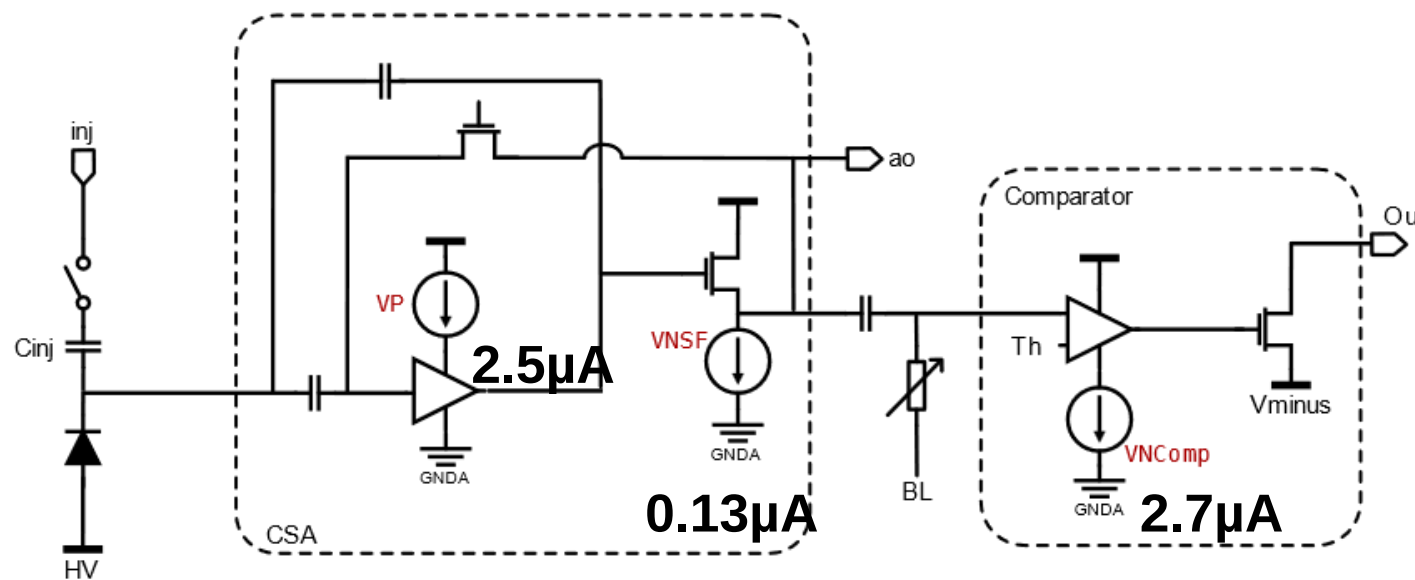
In-Pixel Readout of LF-MightyPix

- Designed and optimized for the 150nm CMOS process
- CSA + Comparator w/ 4bits fine Tuning DAC
 - ENC 150e
 - Threshold distribution is in a tunable range



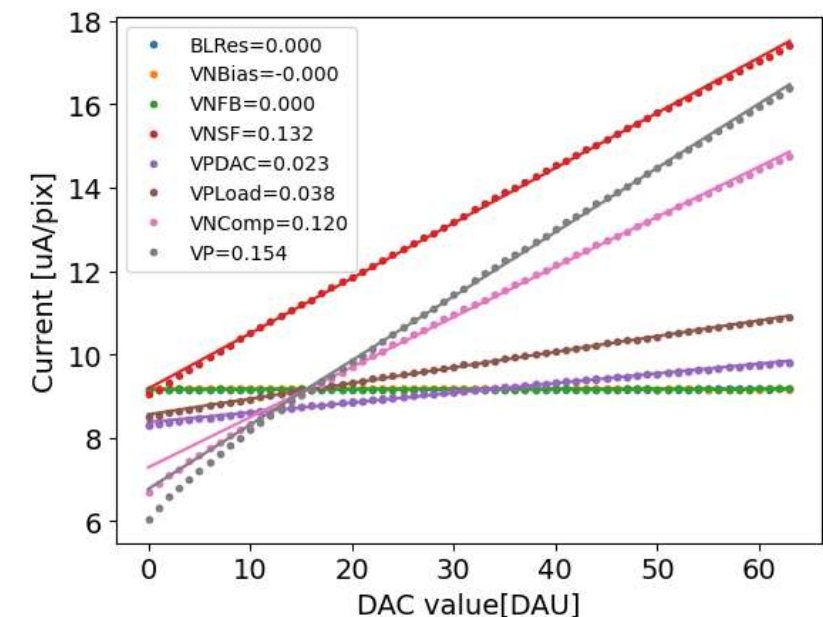
In-Pixel Readout of LF-MightyPix

- CSA + Comparator w/ 3bits fine tuning
- Designed and optimized for the 150nm CMOS process
- Pixel currents are supplied via the current mirrors controlled by DACs.
 - The slope of VDDA current indicate the power consumption of each block per 1DAU



➡ **5.92 $\mu\text{A}/\text{pix}$** (cf. Designed Value = 6 $\mu\text{A}/\text{pix}$)

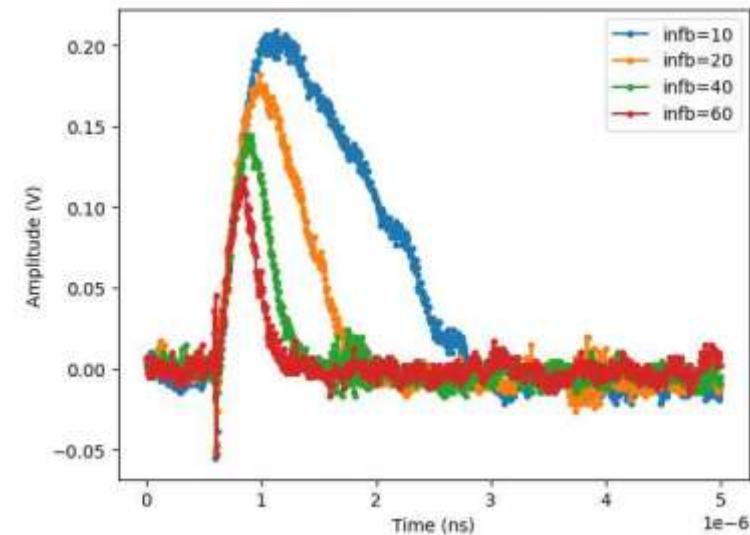
Current Consumption of the Pixels



LF-MightyPix to MightyPix2

- MightyPix1
 - 1.28Gbps data link
- LF-MightyPix
 - 48bits/hit data link with Gear Box
 - TFC
 - Feasibility as a backup process
- **Full reticle chip (P2Pix) from another project**
 - **Pixel Matrix**
 - **Serial Powering**
- MightyPix2 (new features)
 - 4 to 2, 4 to 1 data link Multiplexer
 - 32bits/hit mode
 - DC balanced ECS and TFC decoder
 - SEU hardened digital logics
 - Clock and Resets

Analog output of P2Pix



Y. Su@KIT

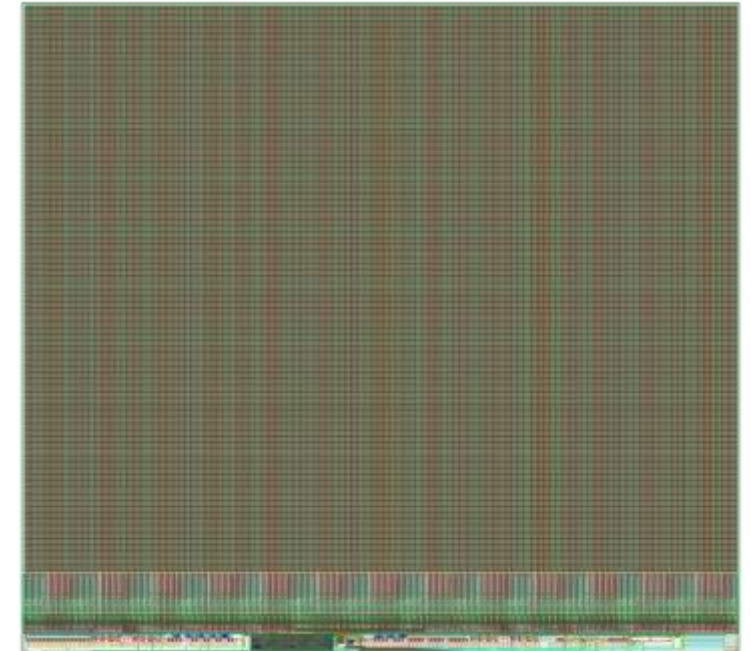
Further tests are on-going

LF-MightyPix to MightyPix2

- Mightypix1
 - 1.28Gbps data link
- LF-Mightypix
 - 48bits/hit data link with Gear Box
 - TFC
- P2Pix
 - Pixel Matrix
 - Serial Powering
- New features
 - 4 to 2, 4 to 1 data link Multiplexer
 - 32bits/hit mode
 - ECS(slow control) and TFC 6b8b decoder
 - SEU hardened digital logics



MightyPix2



Submission: Oct 2025 !

Summary

- LHCb-Control/DAQ compatible HV-MAPS, LF-MightyPix, has been produced using 150nm CMOS process in addition to MightyPix1 (180nm CMOS process, $400\Omega/\text{cm}^2$)
- The test results of sensors and pixel matrix shows feasibility of the 150nm process.
- Experiences in porting Sensor/Readout design ensured a backup plan for long-term projects
- Using results of MightyPix1, LF-MightyPix and chips from other projects, MightyPix 2 has been designed and submitted

